

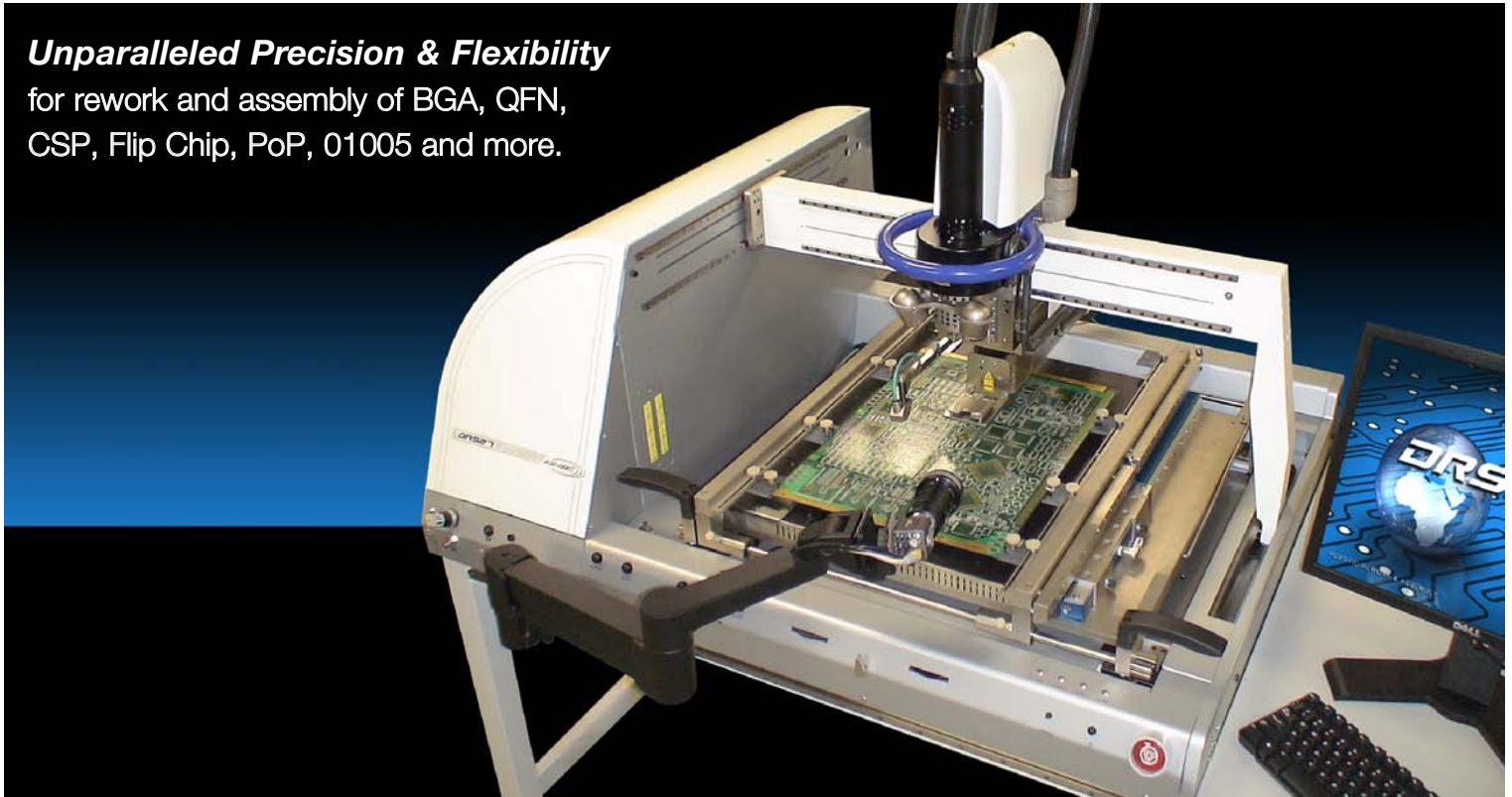
DRS27

SMT Rework & Repair



Unparalleled Precision & Flexibility

for rework and assembly of BGA, QFN, CSP, Flip Chip, PoP, 01005 and more.



High Magnification, High Resolution

State-of-the-Art Vision System

Multiple field-of-view camera allows for extremely close-up viewing of all four corners plus center area of part/location for precision alignment.

Consistent, Precision Vision Alignment

Moveable X/Y Head and Fixed Board Locations

Assemblies remain at a fixed position in the carrier while the overhead robotic head picks, aligns and places components with an 18 micron placement accuracy.

Automatic Component Pick and Place

Motorized Z-Axis & Theta Rotation

Control motion via front mounted joystick control. Programmable component pick-up and adjustable force placement (grams).

Enhanced Force Placement

Load Cells Measure 20-2000 Grams

Programmable Cool Down

Integrated Board Cooling System

Built into the carrier, upper cool air injection bypasses heating element and air flows directly into nozzle (component).

New Expandable Carrier

Preheaters for all Assembly Sizes

- Standard 3-zone preheater, 16" X 24" (XL assemblies)
- Optional 2-zone preheater, 16" X 16"

Excellent Thermal Uniformity

High Efficiency IR Preheater

- Insulated heating elements provide ultra-fast heat up (+/- 5 degrees C).
- Black ceramic, high-emissivity coating dramatically increases radiant energy to produce the significantly higher preheat temperatures required for lead-free rework.
- Excellent for high thermal mass, military type assemblies (metal frames).

Flexible Bottom-Side Clearance

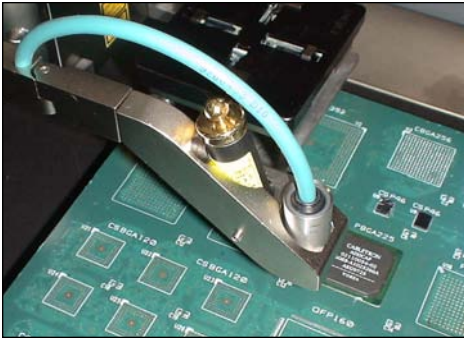
User Adjustable

Keep close for better performance - move away for up to 2" bottom-side clearance.

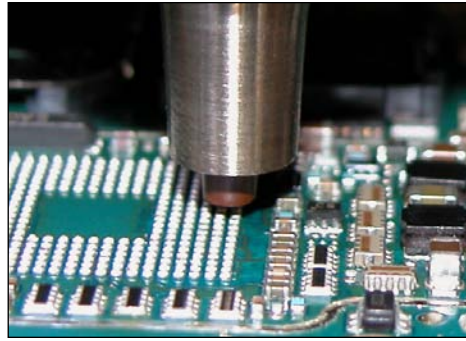
User-Friendly Software

8 Thermocouple Channels

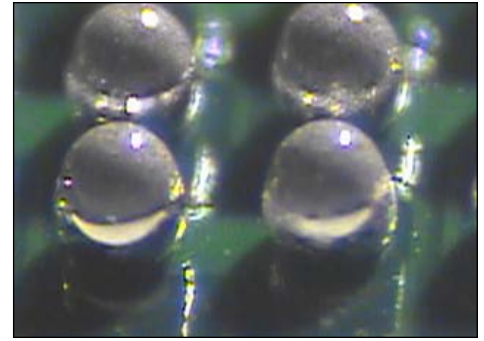
Profile assemblies with Thermal Tutor Software. "On the fly" temperature and air flow adjustments are standard. Profile library and master thermal templates are part of the software package.



PIVOTING IR SENSOR WITH LASER POINTER



STANDARD & MICRO SITE CLEANING



SOLDER PASTE DIPPING KIT

All DRS27 Standard Systems Include:

- 3-Zone, High Efficiency 16" x 24" IR Preheater (7500 watts total)
- Programmable Board Cooling System (Air-Knife)
- 2000 Watt Top Heater
- Cool-Air Injection (Nozzle)
- Motorized Z axis and Theta control
- Multiple Field of View Vision with Top/Bottom LED Lighting, (x and y motor drives)
- 70 mm maximum component size
- Board Carrier Size 18"W x 24"D
- Joystick operation for all motor controls
- 8 Thermocouple Channels
- Welded Steel Frame with Side Table
- Adjustable LED Lighting for PCB
- Thermal Tutor Software
- DELL PC/ Flat Screen Monitor/Keyboard/Mouse
- Tool Kit & Board Supports

Also available:

DRS27-2Z System with:

- 2-Zone, High Efficiency 16" x 16" IR Preheater (5000 watts total)

Recommended Options:

- **Pivoting IR Sensor w/Laser Pointer** (0029.11.041)
Provides process repeatability by insuring that the board is at the exact same target temperature each time
- **Site Cleaning System** (0029.03.012)
Includes standard and micro nozzles for complete removal of site solder.
- **Universal Insertion Tool** (AU6LGA47R)
Mechanically self-centers any device for accurate pick up.
- **Direct View Camera** (0027.15.010)
Provides high magnification site viewing.
- **Dipping Kit for Solder Paste or Flux** (FASET1)
Superior to applying paste via component or board stencils.
- **Ergonomic Workstation with CPU Holder** (1003.05.010)
- **Monitor Stand Option for Workstation** (1003.05.005)
- **Nozzle Stand Option for Workstation** (1003.05.006)
- **Locking Drawer Option for Workstation** (1003.05.007)
- **70mm Topside Clearance** (Std is 30mm) (0029.01.052)
- **Fume Extraction Manifold** (300.00.547)
- **Air Purification Unit** (1020.01.105)
- **Paste-On-Device Stencil Adapter** (0024.24.111)
- **4 Additional Thermocouple Ports** (300.00.504)
- **Colored LED Lighting**